Development of Ultrafast Silicon Sensors for Precision Timing and 4D Tracking

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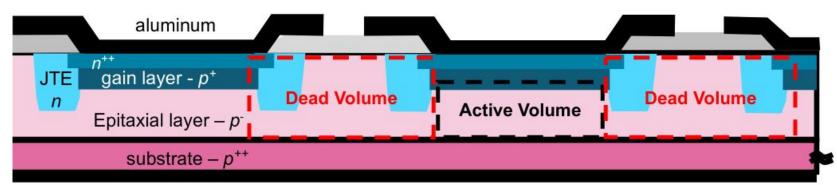
Overview

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Review of LGAD Technology

LGAD Technology

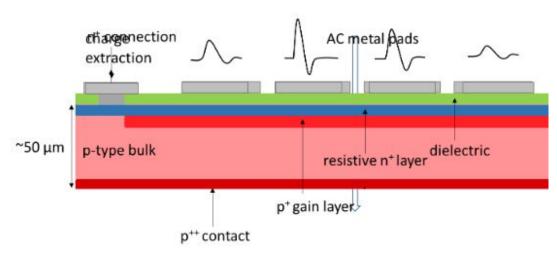
- Low Gain Avalanche Detector (LGAD) is type of silicon based detector that made used of highly doped (p+) layer which provide internal moderate gain of 10 to 50:
 - Very thin active thickness. (20 to 50um).
 - Very Radiation hard (survive up to fluence of 6e15 neq/cm^2)
 - Capable to provide timing resolution < 20 ps for mip.
- However, JTE structure is required to prevent premature breakdown:
 - Large dead area between channels (~30 to 100um)
 - Granularity is limited to mm scale.
- Variant design of LGAD that help resolving this limitation:
 - Maturing design AC-LGAD
 - Promising prototype: Trench-Isolated & Deep-Junction LGAD (focus on this today)

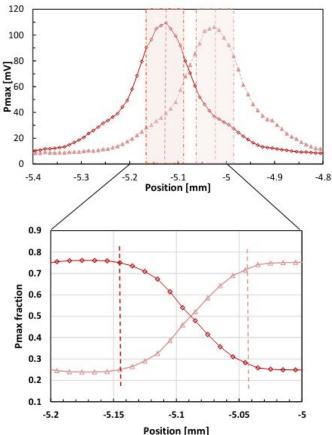


Variant of LGAD Designs

AC-coupled LGAD (AC-LGAD)

- The gain layer is continuous, which contains a highly doped p+ layer and a resistive n+ layer.
- The signal is AC-coupled through a dielectric layer.
- Strong sharing of charge between metal pads.
- Very high fill factor.
- Current development:
 - Pad geometry
 - Impact of strip length
 - Exotic pad geometries possible



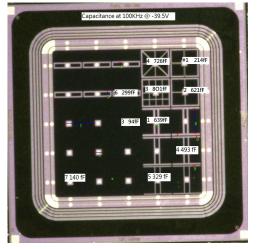


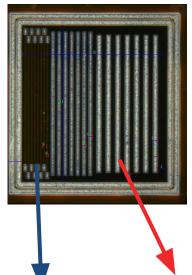
AC-coupled LGAD (AC-LGAD)

 The capacitance of AC-LGAD with different pad geometries and strip length are measured at UCSC.

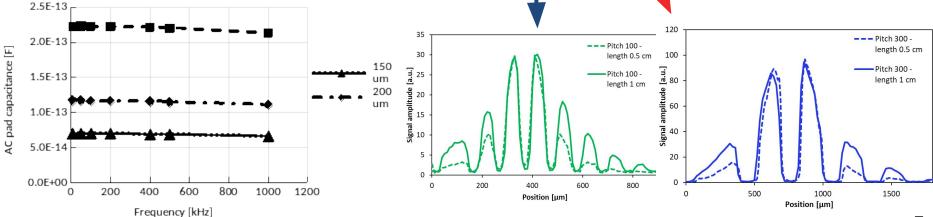
Pad geometries: Reduction of capacitance by decreasing metal

area





Strips: more signal sharing over small pitch, AND more sharing in sensors with longer strips

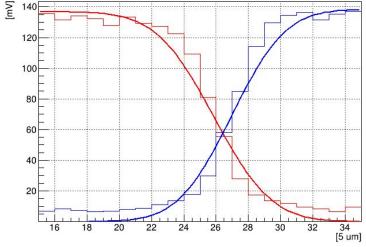


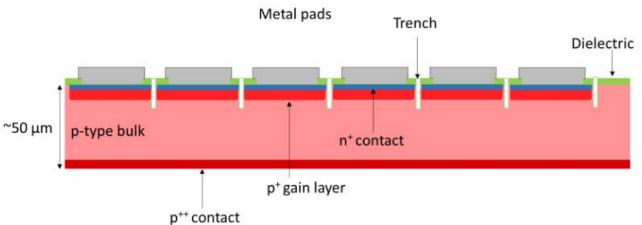
Trench-Isolated LGAD (TI-LGAD)

- DC coupled readout from metal pads.
- Gain layer is segmented with etched trench instead of conventional

JTE structure with implant:

- Very high fill factor.
- No charge sharing.



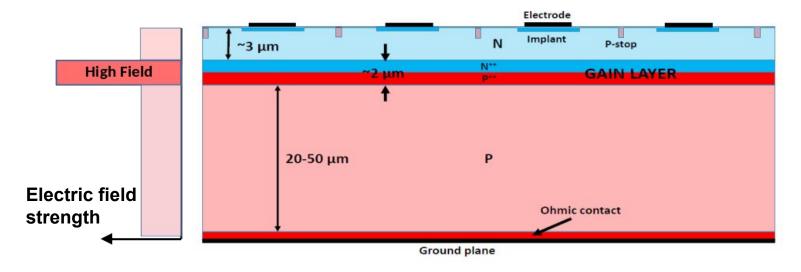


TI-LGAD Produced by FBK

Data taken by **Miguel Godoy**

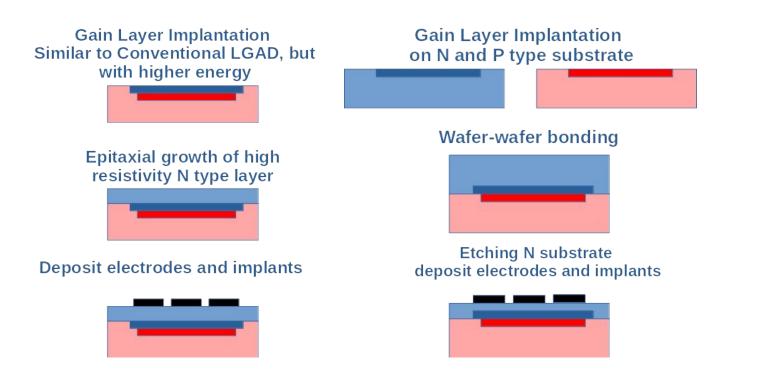
Deep-Junction LGAD Concept

- The term "deep junction" ariase from the use of a p-n junction buried several microns below the surface of the device.
- The Deep Junction concept has several features:
 - The electric field is low at the surface → no JTE structure is required for pixelization/segmentation.
 - The gain layer is continuous across channels, so the dead region is reduced → maintain good charge uniformity
 - Preserved DC coupling of signal to readout electrodes.



DJ-LGAD Prototype Manufacturing

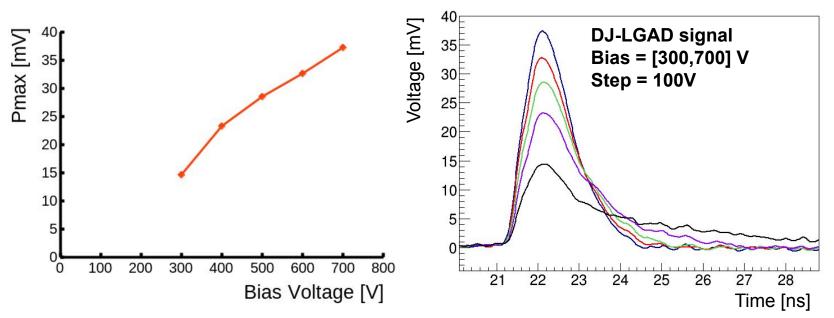
- There are two approaches to achieve deep junction:
 - Epitaxial growing above the deep junction.
 - Wafer-to-wafer bonding (with substrate etching)
- The 2nd DJ-LGAD prototype with wafer-wafer bonding was made in collaboration with Cactus Material Inc & Brookhaven National Laboratory (BNL)



Results from Deep-Junction LGAD Prototype

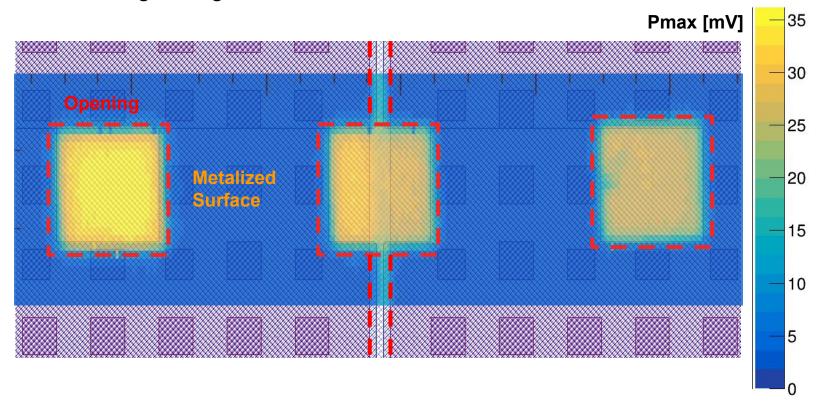
Charge Collection using IR Laser

- IR laser is used for charge injection to study the response.
- The pmax and signals are shown in terms of bias voltage.
 - Rise time ~ 580 ps, similar to a typical 50-60um LGAD.
- Measured gain of ~ 3 to 5,
 - Lower than conventional LGAD
 - Optimization of the gain layer doping is required for future prototype



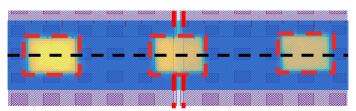
IR Laser TCT Scan

- DJ-LGAD 2x1 array prototype is studied with IR Laser scan.
 - o both pads are readout simultaneous to a digital scope.
- The pmax values in terms of the laser beam location are shown for both channels.
 - o no signal region, color blue, is due to surface metal



Scan over Interpad Region

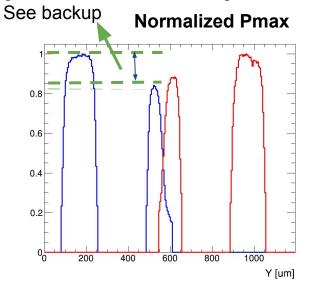
- The pmax projection of the cutline across the two pads are shown:
 - Pmax > 6 is used to remove 3 sigma noise events.

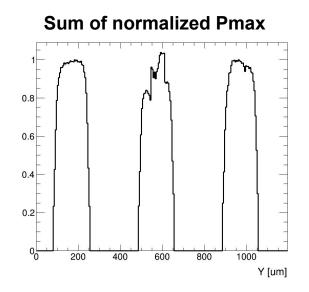


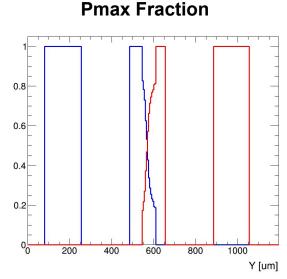
The pmax fraction of an individual strip is defined as:

$$pmax\ fraction\ (channel) = \frac{pmax\ (channel)}{\sum pmax}$$

Field degradation due to geometric effect near IP region.

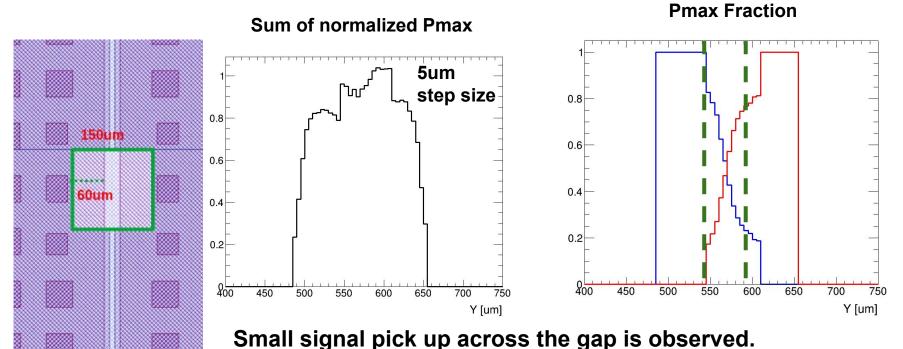






Scan over Interpad Region

- The opening around the interpad region is a 150x150um square
 - The edge of opening to the edge of the pad is 60um
 - The nominal interpad gap is 30 um



No significant signal loss at the gap region, as expected from the continuous gain layer.

Summary

- Presented variant LGAD designs
 - AC-LGAD, TI-LGAD & DJ-LGAD.
- Presented the results of first working DJ-LGAD prototype:
 - The Deep-Junction idea is promising.
 - Shows very good signal/charge uniformity across channels.

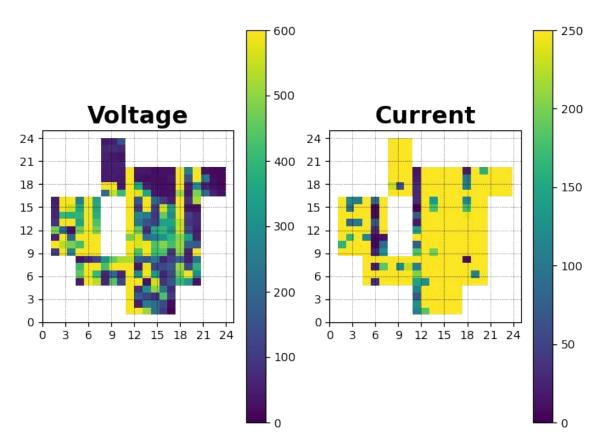
Future production for DJ-LGAD:

- DJ-LGAD currently have very large leakage current, we need to reduce the current to level of conventional LGAD.
- The gain is lower than conventional LGAD, we need to optimize the doping in the future prototype.

Backup

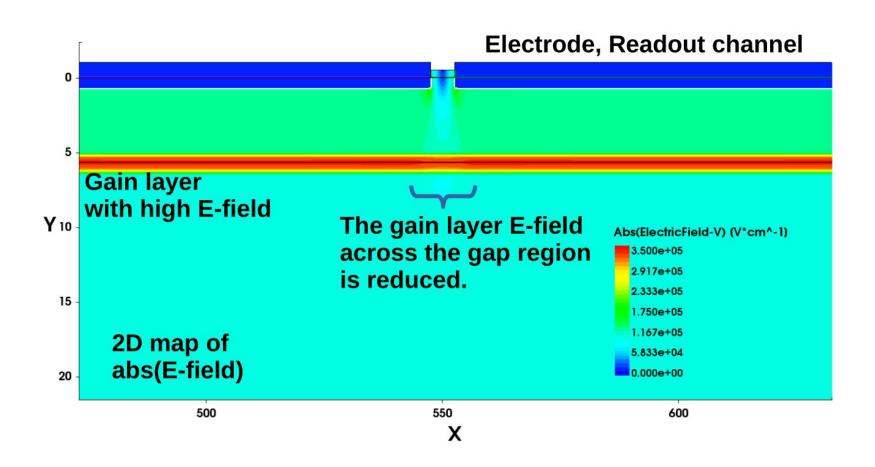
Max Voltage & Current Map

- The DJ-LGAD currently has extremely large leakage current, and breakdown voltage vary significantly across dice over the same wafer.
- The current level is of order of > 100uA.



Field Degradation Cross Pads

 2D simulation shows the field in the gain layer is reduced in the interpad region.



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